

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of :  
Thomas H. DiStefano :  
 :  
 : Group Art Unit:  
Application No. :  
 :  
 : Examiner:  
Filed: May 11, 2001 :  
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 : Date: May 11, 2001  
For: MICROELECTRONIC PACKAGES :  
WITH SOLDER INTERCONNECTIONS :  
X



Commissioner for Patents  
Washington, D.C. 20231

INFORMATION DISCLOSURE STATEMENT

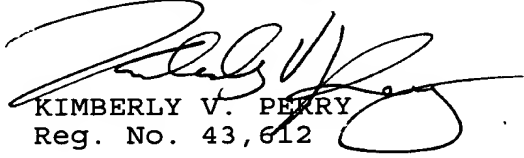
Sir:

It is respectfully requested that the references listed on the enclosed Form PTO-1449 be made of record and considered with respect to the above-referenced U.S. patent application. A copy of each reference was of record in Application No. 09/157,047, the benefit of which is claimed under §120. Submission of the present Information Disclosure Statement should not be taken as an admission that the cited references are legally available prior art or that the same are pertinent or material.

In the event that any fee is due in connection with the present Information Disclosure Statement, the Commissioner is hereby authorized to charge the same to our Deposit Account No. 12-1095.

Respectfully submitted,

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